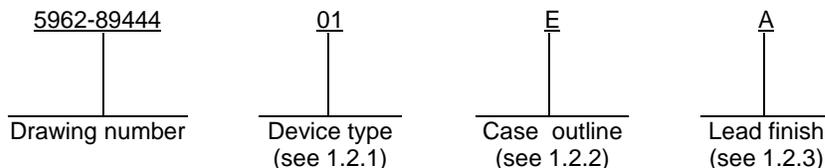


1. SCOPE

1.1 Scope. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.

1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 Device type. The device type identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	54LS597	8-bit shift register with input latches

1.2.2 Case outlines. The case outlines are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
E	GDIP1-T16 or CDIP2-T16	16	dual-in-line
F	GDFP2-F16 or CDFP3-F16	16	flat
2	CQCC1-N20	20	square chip carrier

1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.

1.3 Absolute maximum ratings.

Supply voltage range (V_{CC})	-0.5 V minimum dc to +7.0 V dc maximum
Input voltage range (excluding I/O ports)	-1.5 V dc at -18 mA to +7.0 V dc
Off-state output voltage range (including I/O ports)	-1.5 V dc at -18 mA to +5.5 V dc
Storage temperature range	-65°C to +150°C
Maximum power dissipation (P_D)	291.5 mW ^{1/}
Lead temperature (soldering, 10 seconds)	+300°C
Junction temperature (T_J)	+175°C
Thermal resistance, junction-to-case (θ_{JC})	See MIL-STD-1835

1.4 Recommended operating conditions.

Supply voltage range (V_{CC})	+4.5 V minimum dc to +5.5 V maximum dc
Minimum high level input voltage (V_{IH})	2.0 V dc
Maximum low level input voltage (V_{IL})	0.7 V dc
Maximum input clamp current (I_{IK})	-18 mA
Maximum high level output Current (I_{OH})	-1.0 mA
Maximum low level output current (I_{OL})	8.0 mA
Case operating temperature range (T_C)	-55°C to +125°C

1/ Maximum power dissipation is defined as $V_{CC} \times I_{CC}$, and must withstand the added PD due to short circuit test e.g., IOS.

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1.4 Recommended operating conditions - Continued.

Minimum setup time (t_s):	
Data before RCK \uparrow	20 ns
$\overline{\text{SRCLR}}$ inactive before SRCK \uparrow	25 ns
$\overline{\text{SRLOAD}}$ inactive before SRCK \uparrow	30 ns
RCK \uparrow before $\overline{\text{SRLOAD}}$ \uparrow 2/.....	40 ns
SER before SRCK \uparrow	20 ns
Minimum hold time (t_h)	0 ns
Minimum pulse width (t_w):	
SRCK high	15 ns
SRCK low	35 ns
RCK	20 ns
$\overline{\text{SRCLR}}$	20 ns
$\overline{\text{SRLOAD}}$	40 ns
Maximum shift clock frequency (f_{clock})	20 MHz

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
 MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
 MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <https://assist.daps.dla.mil/quicksearch/> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

2/ The RCK \uparrow before $\overline{\text{SRLOAD}}$ \uparrow setup time ensures the data saved by RCK \uparrow will also be loaded into the shift register.

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3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Truth table. The truth table shall be as specified on figure 2.

3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.5 Test circuit and switching waveforms. The test circuit and switching waveforms shall be as specified on figure 4.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 Marking. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.

3.5.1 Certification/compliance mark. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DLA Land and Maritime -VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change. Notification of change to DLA Land and Maritime -VA shall be required for any change that affects this drawing.

3.9 Verification and review. DLA Land and Maritime, DLA Land and Maritime 's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C ≤ T _c ≤ +125°C +4.5 V ≤ V _{CC} ≤ +5.5 V unless otherwise specified	Group A subgroups	Device type	Limits		Unit	
					Min	Max		
High level output voltage	V _{OH}	V _{CC} = 4.5 V, V _{IL} = 0.7 V, V _{IH} = 2.0 V, I _{OH} = -1 mA	1, 2, 3	All	2.4		V	
Low level output voltage	V _{OL}	V _{CC} = 4.5 V, V _{IL} = 0.7 V, V _{IH} = 2.0 V, I _{OL} = 8 mA	1, 2, 3	All		0.4	V	
Input clamp voltage	V _{IK}	V _{CC} = 4.5 V, I _{IN} = -18 mA	1, 2, 3	All		-1.5	V	
High level input current	I _{IH1}	V _{CC} = 5.5 V, V _{IN} = 2.7 V	1, 2, 3	All		20	μA	
	I _{IH2}	V _{CC} = 5.5 V, V _{IN} = 7.0 V	1, 2, 3	All		0.1	mA	
Low level input current	I _{IL}	V _{CC} = 5.5 V, V _{IN} = 0.4 V	SER, A thru H	1, 2, 3	All		-0.4	mA
			Others	1, 2, 3	All		-0.2	mA
Short circuit output current	I _{OS}	V _{CC} = 5.5 V, V _{OUT} = 0.0 V <u>1/</u>	1, 2, 3	All	-20	-100	mA	
Supply current (total)	I _{CCH}	V _{CC} = 5.5 V, All possible inputs grounded, All outputs open	1, 2, 3	All		53	mA	
	I _{CCL}		1, 2, 3	All		53	mA	
Functional tests		See 4.3.1c, V _{CC} = 4.5 V, 5.5 V	7, 8	All				
Propagation delay time, SRCK↑ to Q _H '	t _{PLH1}	R _L = 1 kΩ C _L = 30 pF see figure 4	9	All		23	ns	
			10, 11	All		32		
	t _{PHL1}		9	All		30	ns	
			10, 11	All		42		
Propagation delay time, SRLOAD ↓ to Q _H '	t _{PLH2}	SRLOAD = Low	9	All		57	ns	
			10, 11	All		80		
	t _{PHL2}		9	All		44	ns	
			10, 11	All		62		
Propagation delay time, SRCLR ↓ to Q _H '	t _{PHL3}	SRLOAD = Low	9	All		36	ns	
			10, 11	All		50		
Propagation delay time, RCK↑ to Q _H '	t _{PLH4}		SRLOAD = Low	9	All		60	ns
				10, 11	All		84	
t _{PHL4}	9	All			48	ns		
	10, 11	All			67			

1/ Not more than one output will be shorted at one time and the duration of the short circuit condition shall not exceed one second.

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Device type	01	
Case outlines	E and F	2
Terminal number	Terminal symbol	
1	B	NC
2	C	B
3	D	C
4	E	D
5	F	E
6	G	NC
7	H	F
8	GND	G
9	Q _{H'}	H
10	$\overline{\text{SRCLR}}$	GND
11	SRCK	NC
12	RCK	Q _{H'}
13	$\overline{\text{SRLOAD}}$	$\overline{\text{SRCLR}}$
14	SER	SRCK
15	A	RCK
16	V _{CC}	NC
17	---	$\overline{\text{SRLOAD}}$
18	---	SER
19	---	A
20	---	V _{CC}

NC = No connection

FIGURE 1. Terminal connections.

RCK	SRCK	$\overline{\text{SRLOAD}}$	$\overline{\text{SRCLR}}$	Function
↑	X	X	X	Data loaded to input latches
↑	X	L	H	Data loaded from inputs to shift register
no clock edge	X	L	H	Data transferred from input latches to shift register
X	X	L	L	Invalid logic; state of shift register indeterminate when signals removed
X	X	H	L	Shift register cleared
X	↑	H	H	Shift register clocked, Q _n = Q _{n-1} , Q ₀ = SER

H = High level voltage
L = Low level voltage
X = Irrelevant
↑ = Low-to-high clock transition

FIGURE 2. Truth table.

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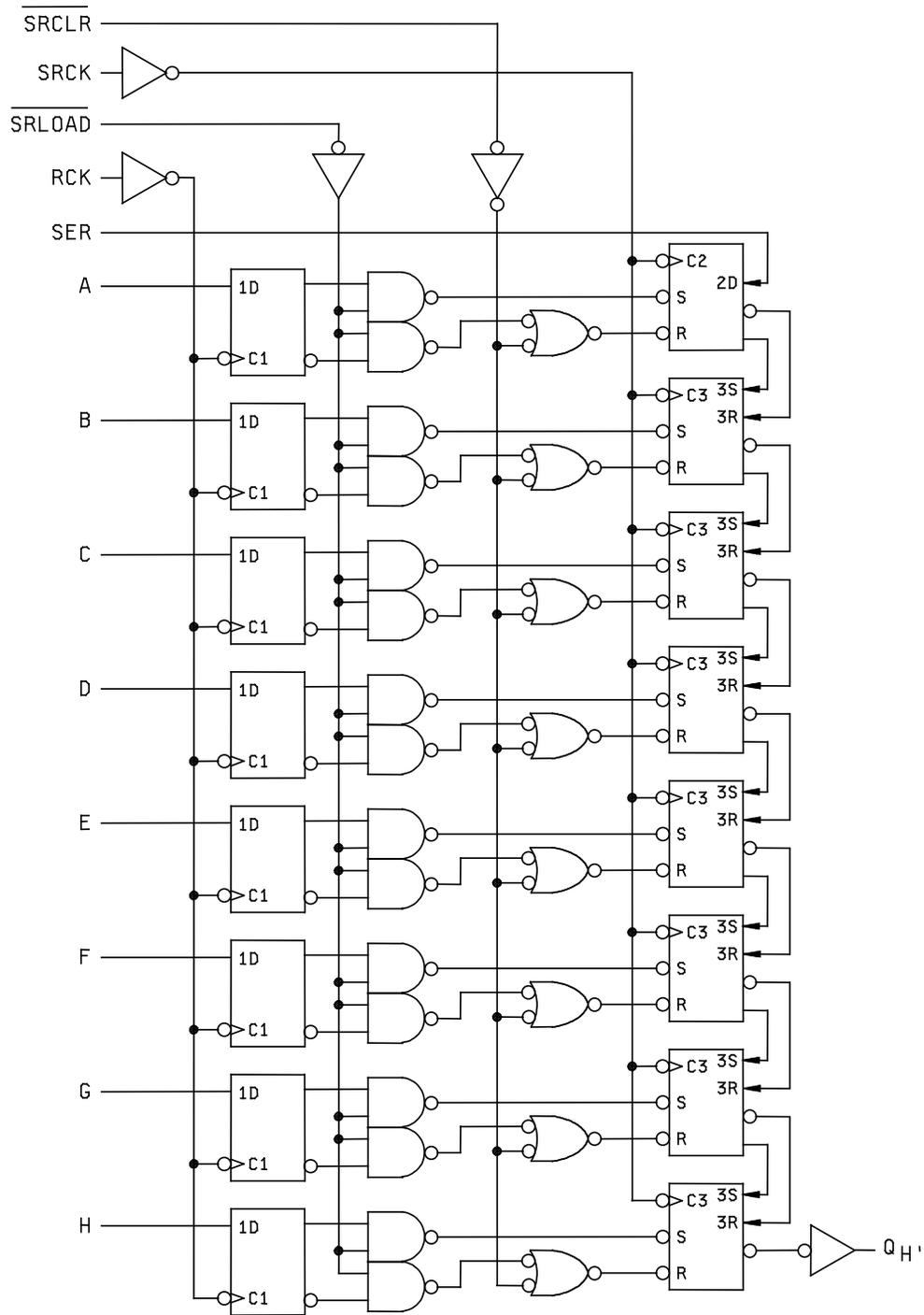


FIGURE 3. Logic diagram.

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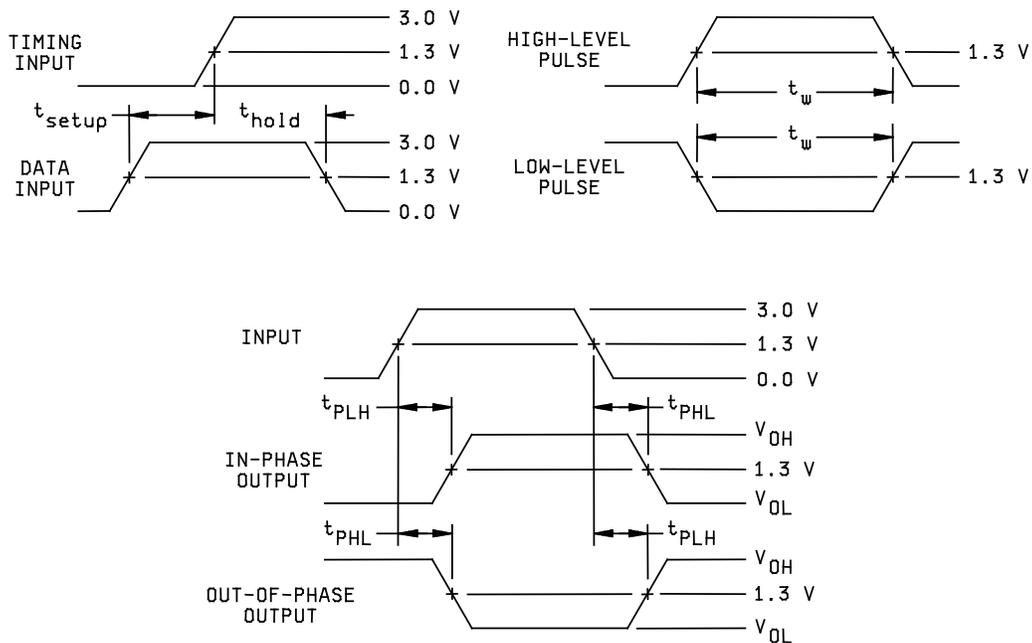
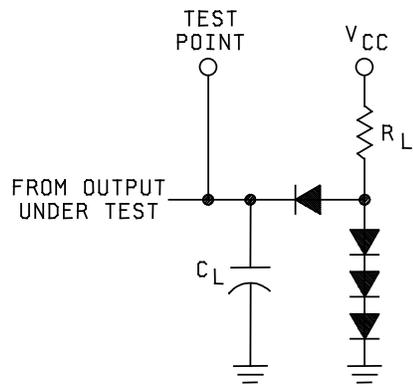
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NOTES:

1. R_L = Load resistor; see table I for value.
2. C_L = Load capacitance includes jig and probe capacitance; see table I for value.
3. All diodes are 1N3064 or equivalent.
4. All input pulses have the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_{OUT} \approx 50\Omega$, $t_r \leq 15 \text{ ns}$, $t_f \leq 6 \text{ ns}$.
5. The outputs are measured one at a time with one input transition per measurement.

FIGURE 3. Test circuit and switching waveforms.

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4. VERIFICATION

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.

(2) $T_A = +125^\circ\text{C}$, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	- - -
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroups 7 and 8 shall include verification of the truth table.

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4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}\text{C}$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.4 Record of users. Military and industrial users shall inform DLA Land and Maritime when a system application requires configuration control and the applicable SMD to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DLA Land and Maritime -VA, telephone (614) 692-0544.

6.5 Comments. Comments on this drawing should be directed to DLA Land and Maritime -VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime -VA.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 12-01-18

Approved sources of supply for SMD 5962-89444 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime -VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <http://www.dscc.dla.mil/Programs/Smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-8944401EA	01295	SNJ54LS597J
5962-8944401FA	01295	SNJ54LS597W
5962-89444012A	01295	SNJ54LS597FK

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE
number

Vendor name
and address

01295

Texas Instruments, Inc.
Semiconductor Group
8505 Forest Ln.
P.O Box 660199
Dallas, TX 75243

POC: U.S. Highway 75 South
P.O. Box 84, M/S 853
Sherman, TX 75090-9493

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